

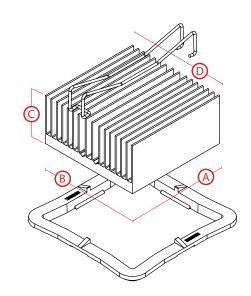
High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment

ATS PART # ATS-53425R-C2-R0

Features & Benefits

- » High aspect ratio, straight fin heat sinks that are ideal for compact PCB environments
- » maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- » Designed specifically for BGAs and other surface mount packages
- » Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock Testing and Unpackaged Drop Testing standards
- » Comes preassembled with high performance thermal interface material

Thermal Performance





*Image above is for illustration purposes only.

AIR VELOCITY				THERMAL RESISTANCE		
F	T/MIN	M/S		°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)	
	200	1.0		3	1.7	
	300 1.5		.5	2.2		
	400 2.0		1.9			
500 2.5		5	1.6			
600		3.0		1.5		
700 3.5		.5	1.4			
800		4	.0	1.3		

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
42.5 mm	42.5 mm	19.5 mm	42.5 mm	SAINT-GOBAIN C675	BLACK-ANODIZED

NOTES:

- Thermal performance data are provided for reference only. Actual performance may vary by application.
- ATS reserves the right to update or change its products without notice to improve the design or performance.
- 4) Optional maxiGRIP™ Installation/Removal Tool Set P/N: MGT425
- 5) Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).

¹⁾ Dimension C = heat sink height from bottom of the base to the top of the fin field.